

D3FK120

Fast Recovery Diodes

1200V, 2.2A

Feature

- Small SMD
- High Voltage
- Low Noise
- Pb free terminal
- RoHS:Yes

OUTLINE

Package (House Name): 2F



Equivalent circuit



Absolute Maximum Ratings (unless otherwise specified : Tl=25°C)

| Item | Symbol | Conditions | Ratings | Unit |
|---------------------------------|---------------------|--|------------|------|
| Storage temperrature | Tstg | | -55 to 150 | °C |
| Junction temperature | Tj | | -55 to 150 | °C |
| Repetitive peak reverse voltage | V _{RRM} | | 1200 | V |
| Average forward current | I _F (AV) | 50Hz sine wave, Resistance load, Tl=81°C | 2.2 | A |
| Average forward current | I _F (AV) | 50Hz sine wave, Resistance load, On glass-epoxy substrate, Ta=25°C ※ | 0.86 | A |
| Surge forward current | I _{FSM} | 50Hz sine wave, Non-repetitive 1 cycle, Peak value, Tj=25°C | 160 | A |

※ :See the original Specifications

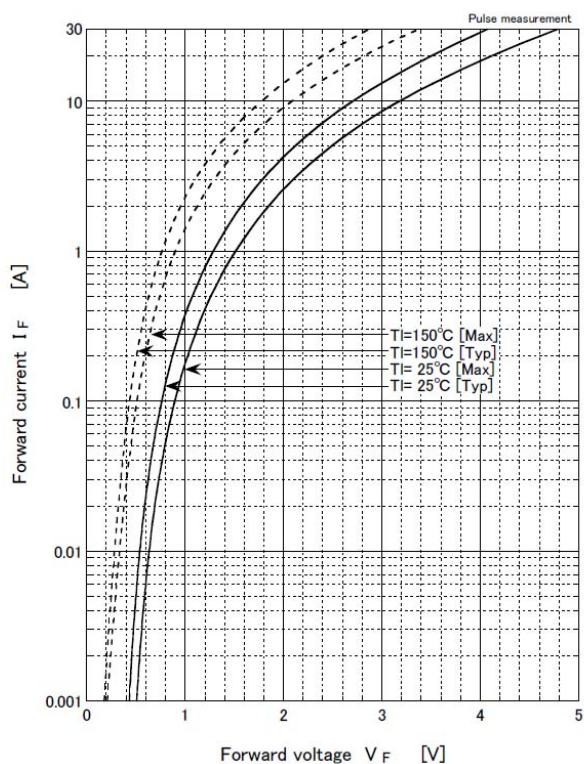
Electrical Characteristics (unless otherwise specified : Tl=25°C)

| Item | Symbol | Conditions | Ratings | | | Unit |
|-----------------------|---------------|---|---------|-----|-----|---------------|
| | | | MIN | TYP | MAX | |
| Forward voltage | V_F | $I_F=3A$, Pulse measurement | | | 2.1 | V |
| Reverse current | I_R | $V_R=1200V$, Pulse measurement | | | 10 | μA |
| Reverse recovery time | t_{rr} | $I_F=0.5A$, $I_R=1.0A$, $0.25I_R$ | | | 80 | ns |
| Total capacitance | C_t | $f=1MHz$, $V_R=10V$ | | 43 | | pF |
| Thermal resistance | $R_{th(j-l)}$ | Junction to lead | | | 16 | $^{\circ}C/W$ |
| Thermal resistance | $R_{th(j-a)}$ | Junction to ambient, On glass-epoxy substrate ※ | | | 115 | $^{\circ}C/W$ |

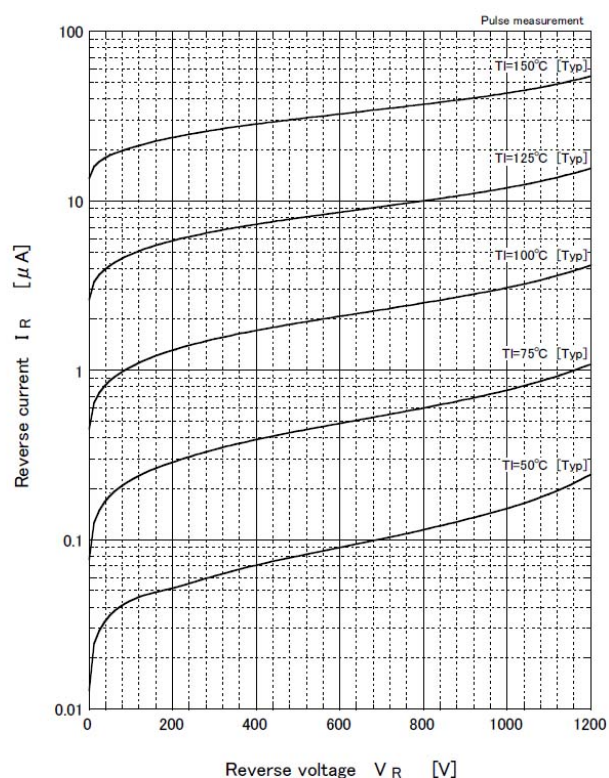
※ :See the original Specifications

CHARACTERISTIC DIAGRAMS

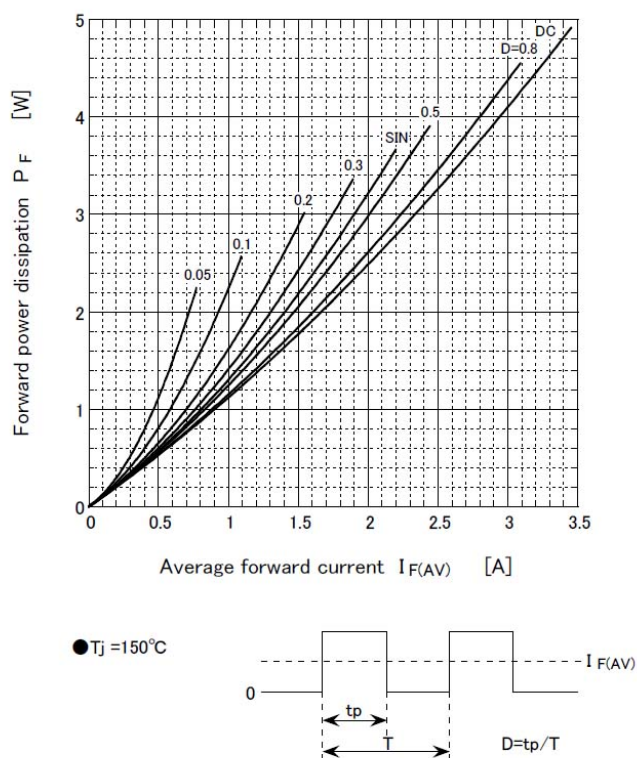
Forward voltage



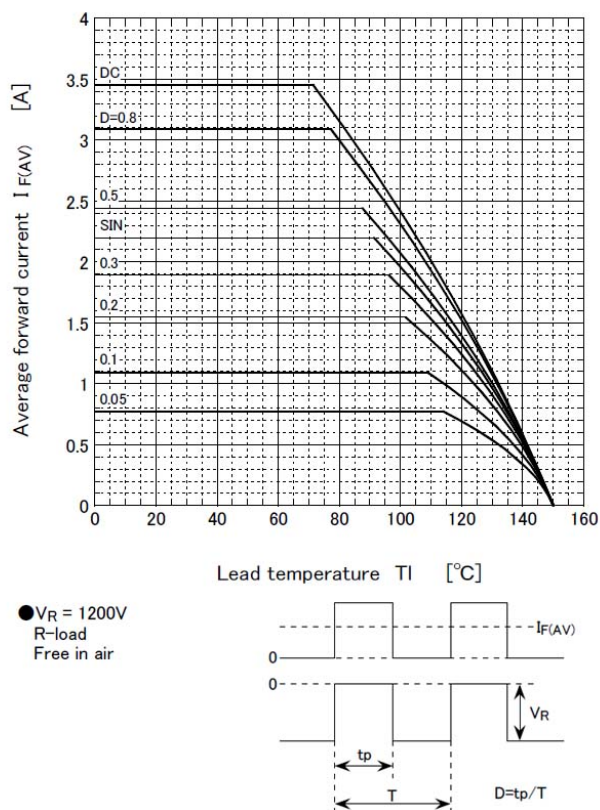
Reverse current



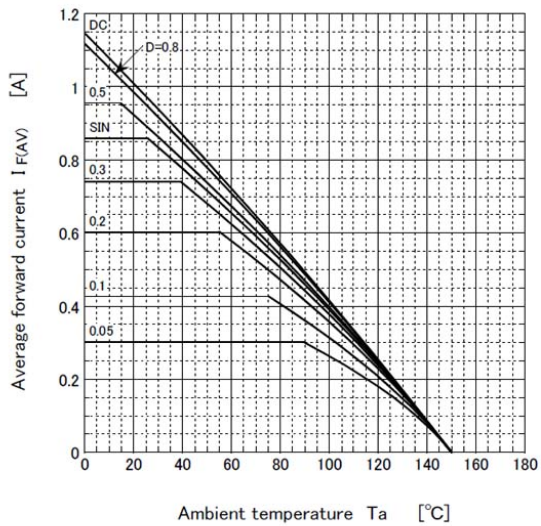
Forward power dissipation



Derating curve



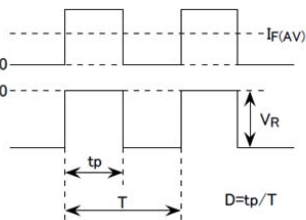
Derating curve



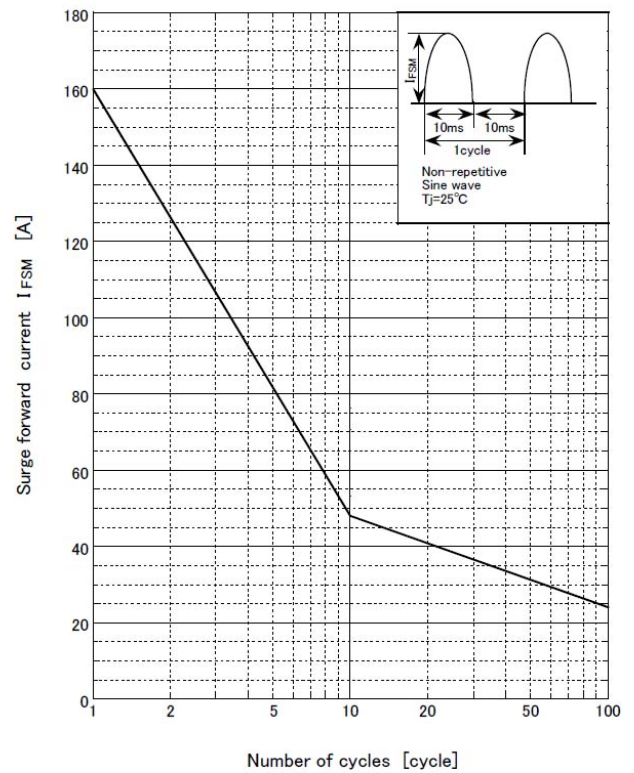
● $V_R = 1200V$
R-load
Free in air

● Substrate detail

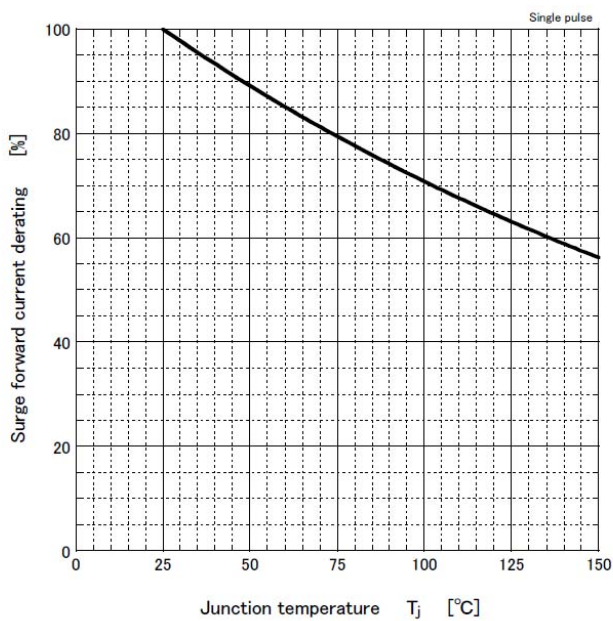
| | |
|---------------------|----------------------|
| Type | Glass-epoxy |
| Size | 1 inch ² |
| Thickness | 1mm |
| Conductor thickness | 35 μm |
| Pattern area | 38.52mm ² |



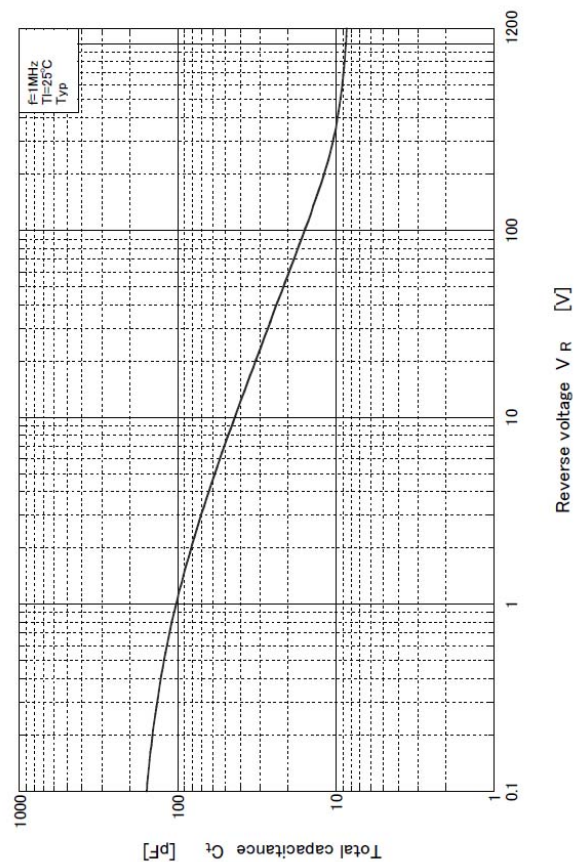
Surge forward current capability



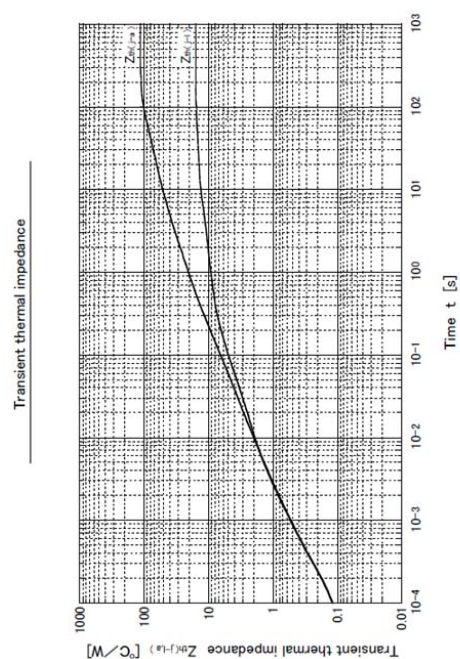
Surge forward current derating vs Junction temperature



Total capacitance



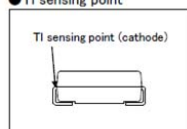
Transient thermal impedance



● Substrate detail

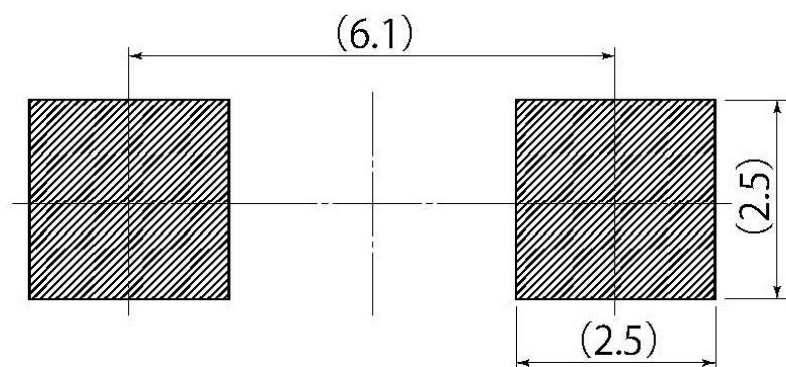
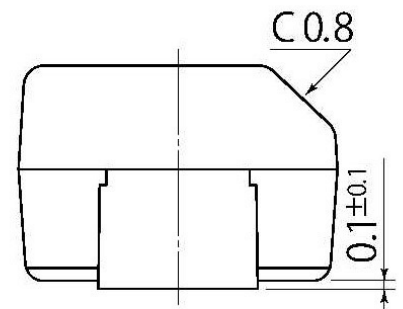
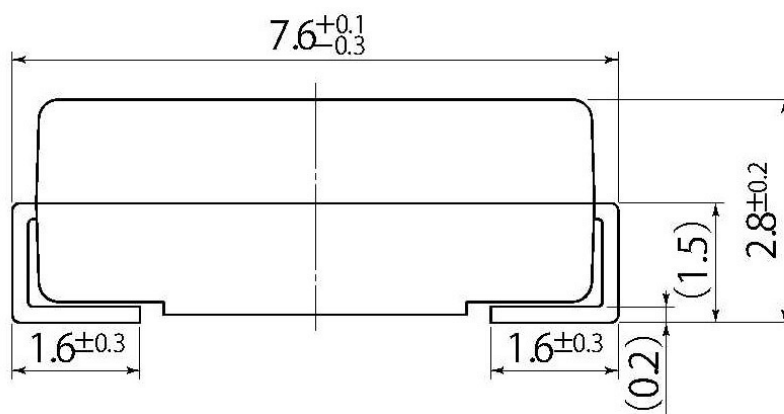
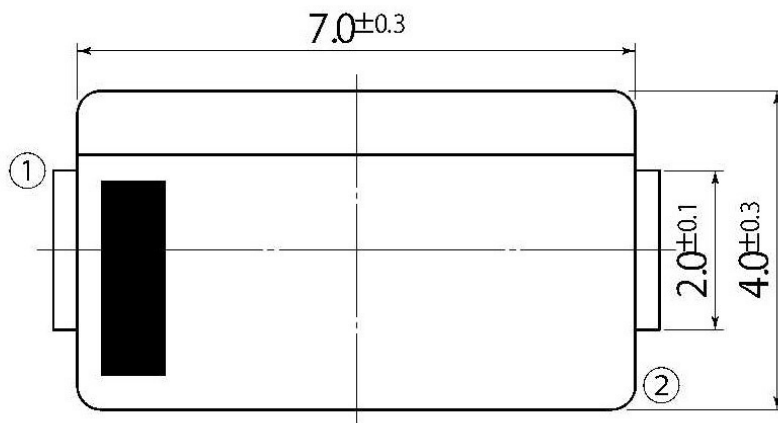
| | |
|---------------------|----------------------|
| Type | Glass-epoxy |
| Size | 1 inch ² |
| Thickness | 1mm |
| Conductor thickness | 35 μm |
| Pattern area | 38.52mm ² |

● TI sensing point



B9

| | |
|------------|----|
| JEDEC Code | — |
| JEITA Code | — |
| House Name | 2F |



Referential Soldering Pad

• Optimize soldering pad to the board design and soldering condition.

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